

PATENT ASSIGNMENT

Electronic Version v1.1

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SUBMISSION TYPE:	NEW ASSIGNMENT						
NATURE OF CONVEYANCE:	ASSIGNMENT						
CONVEYING PARTY DATA							
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Byung-Hyun LEE</td> <td>03/30/2012</td> </tr> <tr> <td>Hoon LEE</td> <td>03/30/2012</td> </tr> </tbody> </table>		Name	Execution Date	Byung-Hyun LEE	03/30/2012	Hoon LEE	03/30/2012
Name	Execution Date						
Byung-Hyun LEE	03/30/2012						
Hoon LEE	03/30/2012						
RECEIVING PARTY DATA							
Name:	Samsung Electronics Co., Ltd.						
Street Address:	416, Maetan-dong, Yeongtong-gu,						
Internal Address:	Gyeonggi-do						
City:	Suwon-si						
State/Country:	KOREA, REPUBLIC OF						
PROPERTY NUMBERS Total: 1							
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13450164</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13450164		
Property Type	Number						
Application Number:	13450164						
CORRESPONDENCE DATA							
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>							
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ATTORNEY DOCKET NUMBER:	Q127301						
NAME OF SUBMITTER:	Jeffrey Heller - Teams Dept.						
Total Attachments: 1 source=Assignment_Executed#page1.tif							

OP \$40.00 13450164

Assignment

Whereas, we, Byung-Hyun LEE and Hoon LEE, both of Seongnam-si, Republic of Korea, hereinafter called assignors, have invented certain improvements in MULTI CHIP PACKAGE, MANUFACTURING METHOD THEREOF, AND MEMORY SYSTEM HAVING THE MULTI CHIP PACKAGE and executed an application for Letters Patent of the United States of America therefor on _____; and

Whereas, Samsung Electronics Co., Ltd. of 416, Maetan-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, Republic of Korea (assignee), desires to acquire the entire right, title, and interest in the application and invention, and to any United States patents to be obtained therefor;

Now therefore, for valuable consideration, receipt whereof is hereby acknowledged,

We, the above named assignors, hereby sell, assign and transfer to the above named assignee, its successors and assigns, the entire right, title and interest in the application and the invention disclosed therein for the United States of America, including all divisions, and continuations thereof, and all Letters Patent of the United States that may be granted thereon, and all reissues thereof, including the right to claim priority under 35 U.S.C. §119, and we request the Director of the U.S. Patent and Trademark Office to issue any Letters Patent granted upon the invention set forth in the application to the assignee, its successors and assigns; and we hereby agree that the assignee may apply for foreign Letters Patent on the invention and we will execute without further consideration all papers deemed necessary by the assignee in connection with the United States and foreign applications when called upon to do so by the assignee.

We hereby authorize and request our attorneys SUGHRUE MION, PLLC of 2100 Pennsylvania Avenue, NW, Washington, DC 20037-3213 to insert here in parentheses (Application number _____ and Confirmation number _____, filed _____) the application number and filing date of said application when known.

Date:

2012.3.30



s/ Byung-Hyun LEE

Date:

2012.3.30



s/ Hoon LEE

(Legalization not required for recording but is prima facie evidence of execution under 35 U.S.C. §261)